

### ABSTRACT

The present invention aims to provide an adhesive composition showing high adhesion and cohesion as well as good heat resistance. Adhesive compositions of the present invention include an imide (meth)acrylate, a monomer having a glass transition temperature of -50 °C or less when it is homopolymerized, and a photoinitiator, wherein the content of the imide (meth)acrylate is 1-20 parts by weight per 100 parts by weight of the monomer.

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